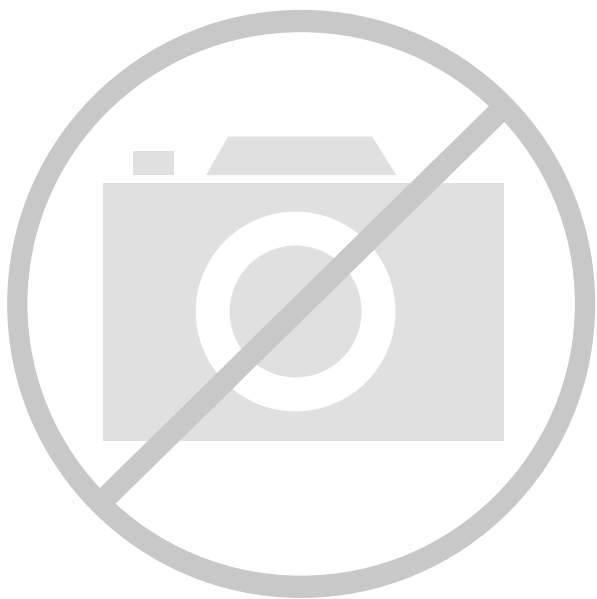




Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

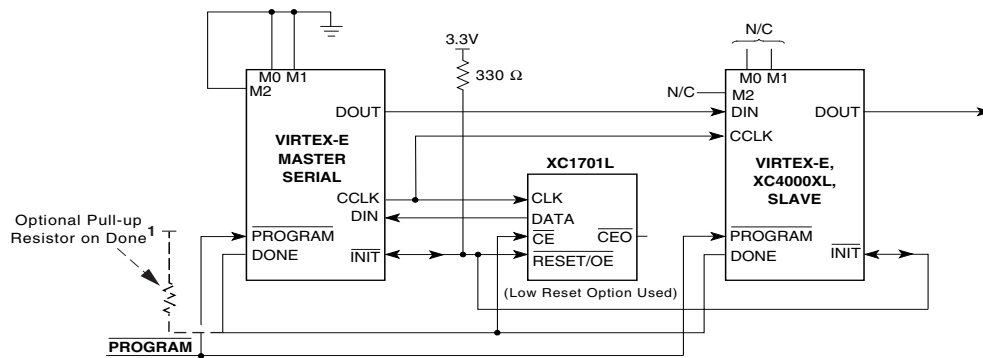
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

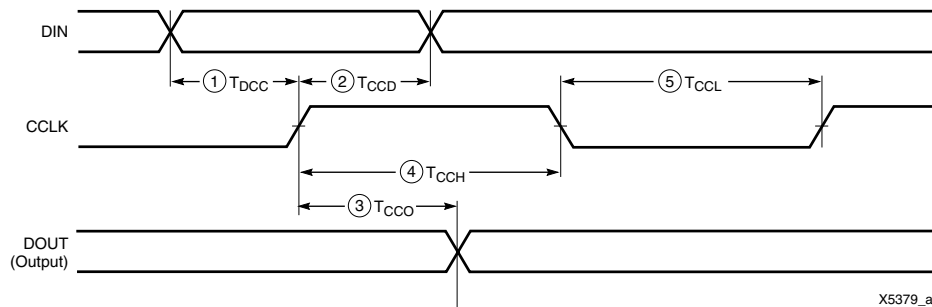
Product Status	Obsolete
Number of LABs/CLBs	6144
Number of Logic Elements/Cells	27648
Total RAM Bits	393216
Number of I/O	158
Number of Gates	1569178
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	240-BFQFP Exposed Pad
Supplier Device Package	240-PQFP (32x32)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv1000e-7hq240i



Note 1: If none of the Virtex FPGAs have been selected to drive DONE, an external pull-up resistor of 330 Ω should be added to the common DONE line. (For Spartan-XL devices, add a 4.7K Ω pull-up resistor.) This pull-up is not needed if the DriveDONE attribute is set. If used, DriveDONE should be selected only for the last device in the configuration chain.

XCVE_ds_013_050103

Figure 13: Master/Slave Serial Mode Circuit Diagram



X5379_a

Figure 14: Slave-Serial Mode Programming Switching Characteristics

Master-Serial Mode

In master-serial mode, the CCLK output of the FPGA drives a Xilinx Serial PROM that feeds bit-serial data to the DIN input. The FPGA accepts this data on each rising CCLK edge. After the FPGA has been loaded, the data for the next device in a daisy-chain is presented on the DOUT pin after the rising CCLK edge. The maximum capacity for a single LOUT/DOUT write is $2^{20}-1$ (1,048,575) 32-bit words, or 33,554,4000 bits.

The interface is identical to slave-serial except that an internal oscillator is used to generate the configuration clock (CCLK). A wide range of frequencies can be selected for CCLK, which always starts at a slow default frequency. Configuration bits then switch CCLK to a higher frequency for the remainder of the configuration. Switching to a lower frequency is prohibited.

The CCLK frequency is set using the ConfigRate option in the bitstream generation software. The maximum CCLK fre-

quency that can be selected is 60 MHz. When selecting a CCLK frequency, ensure that the serial PROM and any daisy-chained FPGAs are fast enough to support the clock rate.

On power-up, the CCLK frequency is approximately 2.5 MHz. This frequency is used until the ConfigRate bits have been loaded when the frequency changes to the selected ConfigRate. Unless a different frequency is specified in the design, the default ConfigRate is 4 MHz.

In a full master/slave system (Figure 13), the left-most device operates in master-serial mode. The remaining devices operate in slave-serial mode. The SPROM RESET pin is driven by INIT, and the CE input is driven by DONE. There is the potential for contention on the DONE pin, depending on the start-up sequence options chosen.

The sequence of operations necessary to configure a Virtex-E FPGA serially appears in Figure 15.

Data Output Bus—DO[AIB]<#:0>

The data out bus reflects the contents of the memory cells referenced by the address bus at the last active clock edge. During a write operation, the data out bus reflects the data in bus. The width of this bus equals the width of the port. The allowed widths appear in [Table 15](#).

Inverting Control Pins

The four control pins (CLK, EN, WE and RST) for each port have independent inversion control as a configuration option.

Address Mapping

Each port accesses the same set of 4096 memory cells using an addressing scheme dependent on the width of the port.

The physical RAM location addressed for a particular width are described in the following formula (of interest only when the two ports use different aspect ratios).

$$\text{Start} = ((\text{ADDR}_{\text{port}} + 1) * \text{Width}_{\text{port}}) - 1$$

$$\text{End} = \text{ADDR}_{\text{port}} * \text{Width}_{\text{port}}$$

Conflict Resolution

The block SelectRAM+ memory is a true dual-read/write port RAM that allows simultaneous access of the same memory cell from both ports. When one port writes to a given memory cell, the other port must not address that memory cell (for a write or a read) within the clock-to-clock setup window. The following lists specifics of port and memory cell write conflict resolution.

- If both ports write to the same memory cell simultaneously, violating the clock-to-clock setup requirement, consider the data stored as invalid.
- If one port attempts a read of the same memory cell the other simultaneously writes, violating the clock-to-clock setup requirement, the following occurs.
 - The write succeeds
 - The data out on the writing port accurately reflects the data written.
 - The data out on the reading port is invalid.

Conflicts do not cause any physical damage.

[Table 16](#) shows low order address mapping for each port width.

Table 16: Port Address Mapping

Port Width	Port Addresses																
1	4095...	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
2	2047...	07		06		05		04		03		02		01		00	
4	1023...	03				02				01				00			
8	511...	01								00							
16	255...	00															

Creating Larger RAM Structures

The block SelectRAM+ columns have specialized routing to allow cascading blocks together with minimal routing delays. This achieves wider or deeper RAM structures with a smaller timing penalty than when using normal routing channels.

Location Constraints

Block SelectRAM+ instances can have LOC properties attached to them to constrain the placement. The block SelectRAM+ placement locations are separate from the CLB location naming convention, allowing the LOC properties to transfer easily from array to array.

The LOC properties use the following form.

$$\text{LOC} = \text{RAMB4_R\#C\#}$$

RAMB4_R0C0 is the upper left RAMB4 location on the device.

Single Port Timing

[Figure 33](#) shows a timing diagram for a single port of a block SelectRAM+ memory. The block SelectRAM+ AC switching characteristics are specified in the data sheet. The block SelectRAM+ memory is initially disabled.

At the first rising edge of the CLK pin, the ADDR, DI, EN, WE, and RST pins are sampled. The EN pin is High and the WE pin is Low indicating a read operation. The DO bus contains the contents of the memory location, 0x00, as indicated by the ADDR bus.

At the second rising edge of the CLK pin, the ADDR, DI, EN, WR, and RST pins are sampled again. The EN and WE pins are High indicating a write operation. The DO bus mirrors the DI bus. The DI bus is written to the memory location 0x0F.

At the third rising edge of the CLK pin, the ADDR, DI, EN, WR, and RST pins are sampled again. The EN pin is High and the WE pin is Low indicating a read operation. The DO bus contains the contents of the memory location 0x7E as indicated by the ADDR bus.

At the fourth rising edge of the CLK pin, the ADDR, DI, EN, WR, and RST pins are sampled again. The EN pin is Low

IOB Flip-Flop/Latch Property

The Virtex-E series I/O Block (IOB) includes an optional register on the input path, an optional register on the output path, and an optional register on the 3-state control pin. The design implementation software automatically takes advantage of these registers when the following option for the Map program is specified.

```
map -pr b <filename>
```

Alternatively, the IOB = TRUE property can be placed on a register to force the mapper to place the register in an IOB.

Location Constraints

Specify the location of each SelectI/O symbol with the location constraint LOC attached to the SelectI/O symbol. The external port identifier indicates the value of the location constrain. The format of the port identifier depends on the package chosen for the specific design.

The LOC properties use the following form:

```
LOC=A42
```

```
LOC=P37
```

Output Slew Rate Property

As mentioned above, a variety of symbol names provide the option of choosing the desired slew rate for the output buffers. In the case of the LVTTTL output buffers (OBUF, OBUFT, and IOBUF), slew rate control can be alternatively programmed with the SLEW= property. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals. The SLEW= property has one of the two following values.

```
SLEW=SLOW
```

```
SLEW=FAST
```

Output Drive Strength Property

The desired output drive strength can be additionally specified by choosing the appropriate library symbol. The Xilinx library also provides an alternative method for specifying this feature. For the LVTTTL output buffers (OBUF, OBUFT, and IOBUF), the desired drive strength can be specified with the DRIVE= property. This property could have one of the following seven values.

```
DRIVE=2
```

```
DRIVE=4
```

```
DRIVE=6
```

```
DRIVE=8
```

```
DRIVE=12 (Default)
```

```
DRIVE=16
```

```
DRIVE=24
```

Design Considerations

Reference Voltage (V_{REF}) Pins

Low-voltage I/O standards with a differential amplifier input buffer require an input reference voltage (V_{REF}). Provide the V_{REF} as an external signal to the device.

The voltage reference signal is “banked” within the device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See [Figure 38](#) for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

Within each V_{REF} bank, any input buffers that require a V_{REF} signal must be of the same type. Output buffers of any type and input buffers can be placed without requiring a reference voltage within the same V_{REF} bank.

Output Drive Source Voltage (V_{CCO}) Pins

Many of the low voltage I/O standards supported by SelectI/O devices require a different output drive source voltage (V_{CCO}). As a result each device can often have to support multiple output drive source voltages.

The Virtex-E series supports eight banks for the HQ and PQ packages. The CS package supports four V_{CCO} banks.

Output buffers within a given V_{CCO} bank must share the same output drive source voltage. Input buffers for LVTTTL, LVCMOS2, LVCMOS18, PCI33_3, and PCI 66_3 use the V_{CCO} voltage for Input V_{CCO} voltage.

Transmission Line Effects

The delay of an electrical signal along a wire is dominated by the rise and fall times when the signal travels a short distance. Transmission line delays vary with inductance and capacitance, but a well-designed board can experience delays of approximately 180 ps per inch.

Transmission line effects, or reflections, typically start at 1.5" for fast (1.5 ns) rise and fall times. Poor (or non-existent) termination or changes in the transmission line impedance cause these reflections and can cause additional delay in longer traces. As system speeds continue to increase, the effect of I/O delays can become a limiting factor and therefore transmission line termination becomes increasingly more important.

Termination Techniques

A variety of termination techniques reduce the impact of transmission line effects.

The following are output termination techniques:

- None
- Series
- Parallel (Shunt)
- Series and Parallel (Series-Shunt)

SSTL2_II

A sample circuit illustrating a valid termination technique for SSTL2_II appears in Figure 52. DC voltage specifications appear in Table 31.

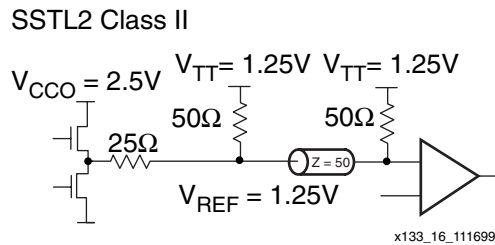


Figure 52: Terminated SSTL2 Class II

Table 31: SSTL2_II Voltage Specifications

Parameter	Min	Typ	Max
V_{CCO}	2.3	2.5	2.7
$V_{REF} = 0.5 \times V_{CCO}$	1.15	1.25	1.35
$V_{TT} = V_{REF} + N^{(1)}$	1.11	1.25	1.39
$V_{IH} = V_{REF} + 0.18$	1.33	1.43	3.0 ⁽²⁾
$V_{IL} = V_{REF} - 0.18$	-0.3 ⁽³⁾	1.07	1.17
$V_{OH} = V_{REF} + 0.8$	1.95	-	-
$V_{OL} = V_{REF} - 0.8$	-	-	0.55
I_{OH} at V_{OH} (mA)	-15.2	-	-
I_{OL} at V_{OL} (mA)	15.2	-	-

Notes:

1. N must be greater than or equal to -0.04 and less than or equal to 0.04.
2. V_{IH} maximum is $V_{CCO} + 0.3$.
3. V_{IL} minimum does not conform to the formula.

CTT

A sample circuit illustrating a valid termination technique for CTT appear in Figure 53. DC voltage specifications appear in Table 32.

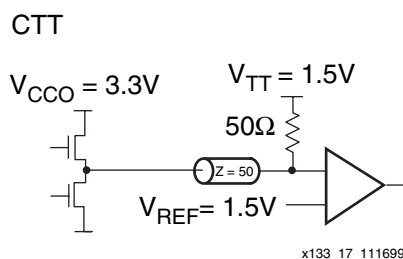


Figure 53: Terminated CTT

Table 32: CTT Voltage Specifications

Parameter	Min	Typ	Max
V_{CCO}	2.05 ⁽¹⁾	3.3	3.6
V_{REF}	1.35	1.5	1.65
V_{TT}	1.35	1.5	1.65
$V_{IH} = V_{REF} + 0.2$	1.55	1.7	-
$V_{IL} = V_{REF} - 0.2$	-	1.3	1.45
$V_{OH} = V_{REF} + 0.4$	1.75	1.9	-
$V_{OL} = V_{REF} - 0.4$	-	1.1	1.25
I_{OH} at V_{OH} (mA)	-8	-	-
I_{OL} at V_{OL} (mA)	8	-	-

Notes:

1. Timing delays are calculated based on V_{CCO} min of 3.0V.

PCI33_3 & PCI66_3

PCI33_3 or PCI66_3 require no termination. DC voltage specifications appear in Table 33.

Table 33: PCI33_3 and PCI66_3 Voltage Specifications

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
V_{REF}	-	-	-
V_{TT}	-	-	-
$V_{IH} = 0.5 \times V_{CCO}$	1.5	1.65	$V_{CCO} + 0.5$
$V_{IL} = 0.3 \times V_{CCO}$	-0.5	0.99	1.08
$V_{OH} = 0.9 \times V_{CCO}$	2.7	-	-
$V_{OL} = 0.1 \times V_{CCO}$	-	-	0.36
I_{OH} at V_{OH} (mA)	Note 1	-	-
I_{OL} at V_{OL} (mA)	Note 1	-	-

Notes:

1. Tested according to the relevant specification.

Termination Resistor Packs

Resistor packs are available with the values and the configuration required for LVDS and LVPECL termination from Bourns, Inc., as listed in Table. For pricing and availability, please contact Bourns directly at <http://www.bourns.com>.

Table 40: Bourns LVDS/LVPECL Resistor Packs

Part Number	I/O Standard	Term. for:	Pairs/ Pack	Pins
CAT16-LV2F6	LVDS	Driver	2	8
CAT16-LV4F12	LVDS	Driver	4	16
CAT16-PC2F6	LVPECL	Driver	2	8
CAT16-PC4F12	LVPECL	Driver	4	16
CAT16-PT2F2	LVDS/LVPECL	Receiver	2	8
CAT16-PT4F4	LVDS/LVPECL	Receiver	4	16

LVDS Design Guide

The SelectI/O library elements have been expanded for Virtex-E devices to include new LVDS variants. At this time all of the cells might not be included in the Synthesis libraries. The 2.1i-Service Pack 2 update for Alliance and Foundation software includes these cells in the VHDL and Verilog libraries. It is necessary to combine these cells to create the P-side (positive) and N-side (negative) as described in the input, output, 3-state and bidirectional sections.

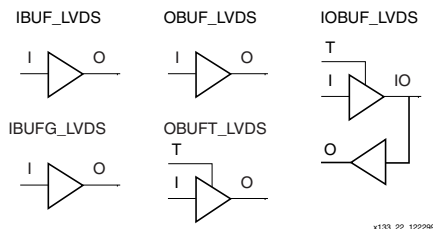


Figure 58: LVDS elements

Creating LVDS Global Clock Input Buffers

Global clock input buffers can be combined with adjacent IOBs to form LVDS clock input buffers. P-side is the GCLK-PAD location; N-side is the adjacent IO_LVDS_DLL site.

Table 41: Global Clock Input Buffer Pair Locations

Pkg	GCLK 3		GCLK 2		GCLK 1		GCLK 0	
	P	N	P	N	P	N	P	N
CS144	A6	C6	A7	B7	M7	M6	K7	N8
PQ240	P213	P215	P210	P209	P89	P87	P92	P93
HQ240	P213	P215	P210	P209	P89	P87	P92	P93
BG352	D14	A15	B14	A13	AF14	AD14	AE13	AC13
BG432	D17	C17	A16	B16	AK16	AL17	AL16	AH15
BG560	A17	C18	D17	E17	AJ17	AM18	AL17	AM17
FG256	B8	A7	C9	A8	R8	T8	N8	N9
FG456	C11	B11	A11	D11	Y11	AA11	W12	U12
FG676	E13	B13	C13	F14	AB13	AF13	AA14	AC14
FG680	A20	C22	D21	A19	AU22	AT22	AW19	AT21
FG860	C22	A22	B22	D22	AY22	AW21	BA22	AW20
FG900	C15	A15	E15	E16	AK16	AH16	AJ16	AF16
FG1156	E17	C17	D17	J18	AI19	AL17	AH18	AM18

HDL Instantiation

Only one global clock input buffer is required to be instantiated in the design and placed on the correct GCLKPAD location. The N-side of the buffer is reserved and no other IOB is allowed to be placed on this location.

In the physical device, a configuration option is enabled that routes the pad wire to the differential input buffer located in the GCLKIOB. The output of this buffer then drives the output of the GCLKIOB cell. In EPIC it appears that the second buffer is unused. Any attempt to use this location for another purpose leads to a DRC error in the software.

VHDL Instantiation

```
gclk0_p : IBUFG_LVDS port map
(I=>clk_external, O=>clk_internal);
```

Verilog Instantiation

```
IBUFG_LVDS gclk0_p (.I(clk_external),
.O(clk_internal));
```

Location constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET clk_external LOC = GCLKPAD3;
```

GCLKPAD3 can also be replaced with the package pin name such as D17 for the BG432 package.

Optional N-side

Some designers might prefer to also instantiate the N-side buffer for the global clock buffer. This allows the top-level net list to include net connections for both PCB layout and system-level integration. In this case, only the output P-side IBUFG connection has a net connected to it. Since the N-side IBUFG does not have a connection in the EDIF net list, it is trimmed from the design in MAP.

VHDL Instantiation

```
gclk0_p : IBUFG_LVDS port map
(I=>clk_p_external, O=>clk_internal);

gclk0_n : IBUFG_LVDS port map
(I=>clk_n_external, O=>clk_internal);
```

Verilog Instantiation

```
IBUFG_LVDS gclk0_p (.I(clk_p_external),
.O(clk_internal));

IBUFG_LVDS gclk0_n (.I(clk_n_external),
.O(clk_internal));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET clk_p_external LOC = GCLKPAD3;

NET clk_n_external LOC = C17;
```

GCLKPAD3 can also be replaced with the package pin name, such as D17 for the BG432 package.

Creating LVDS Input Buffers

An LVDS input buffer can be placed in a wide number of IOB locations. The exact location is dependent on the package that is used. The Virtex-E package information lists the possible locations as IO_L#P for the P-side and IO_L#N for the N-side where # is the pair number.

HDL Instantiation

Only one input buffer is required to be instantiated in the design and placed on the correct IO_L#P location. The N-side of the buffer is reserved and no other IOB is allowed to be placed on this location. In the physical device, a configuration option is enabled that routes the pad wire from the IO_L#N IOB to the differential input buffer located in the IO_L#P IOB. The output of this buffer then drives the output of the IO_L#P cell or the input register in the IO_L#P IOB. In EPIC it appears that the second buffer is unused. Any attempt to use this location for another purpose leads to a DRC error in the software.

VHDL Instantiation

```
data0_p : IBUF_LVDS port map (I=>data(0),
O=>data_int(0));
```

Verilog Instantiation

```
IBUF_LVDS data0_p (.I(data[0]),
.O(data_int[0]));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data<0> LOC = D28; # IO_L0P
```

Optional N-side

Some designers might prefer to also instantiate the N-side buffer for the input buffer. This allows the top-level net list to include net connections for both PCB layout and system-level integration. In this case, only the output P-side IBUF connection has a net connected to it. Since the N-side IBUF does not have a connection in the EDIF net list, it is trimmed from the design in MAP.

VHDL Instantiation

```
data0_p : IBUF_LVDS port map
(I=>data_p(0), O=>data_int(0));

data0_n : IBUF_LVDS port map
(I=>data_n(0), O=>open);
```

Verilog Instantiation

```
IBUF_LVDS data0_p (.I(data_p[0]),
.O(data_int[0]));

IBUF_LVDS data0_n (.I(data_n[0]), .O());
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data_p<0> LOC = D28; # IO_L0P

NET data_n<0> LOC = B29; # IO_L0N
```

Adding an Input Register

All LVDS buffers can have an input register in the IOB. The input register is in the P-side IOB only. All the normal IOB register options are available (FD, FDE, FDC, FDCE, FDP, FDPE, FDR, FDRE, FDS, FDSE, LD, LDE, LDC, LDCE, LDP, LDPE). The register elements can be inferred or explicitly instantiated in the HDL code.

The register elements can be packed in the IOB using the IOB property to TRUE on the register or by using the “map-pr [ilolb]” where “i” is inputs only, “o” is outputs only and “b” is both inputs and outputs.

To improve design coding times VHDL and Verilog synthesis macro libraries available to explicitly create these structures. The input library macros are listed in Table 42. The I and IB inputs to the macros are the external net connections.

DC Characteristics

Absolute Maximum Ratings

Symbol	Description ⁽¹⁾			Units
V_{CCINT}	Internal Supply voltage relative to GND		–0.5 to 2.0	V
V_{CCO}	Supply voltage relative to GND		–0.5 to 4.0	V
V_{REF}	Input Reference Voltage		–0.5 to 4.0	V
$V_{IN}^{(3)}$	Input voltage relative to GND		–0.5 to $V_{CCO} + 0.5$	V
V_{TS}	Voltage applied to 3-state output		–0.5 to 4.0	V
V_{CC}	Longest Supply Voltage Rise Time from 0 V - 1.71 V		50	ms
T_{STG}	Storage temperature (ambient)		–65 to +150	°C
T_J	Junction temperature ⁽²⁾	Plastic packages	+125	°C

Notes:

- Stresses beyond those listed under Absolute Maximum Ratings can cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time can affect device reliability.
- For soldering guidelines and thermal considerations, see the device packaging information on www.xilinx.com.
- Inputs configured as PCI are fully PCI compliant. This statement takes precedence over any specification that would imply that the device is not PCI compliant.

Recommended Operating Conditions

Symbol	Description		Min	Max	Units
V_{CCINT}	Internal Supply voltage relative to GND, $T_J = 0\text{ °C to }+85\text{ °C}$	Commercial	1.8 – 5%	1.8 + 5%	V
	Internal Supply voltage relative to GND, $T_J = -40\text{ °C to }+100\text{ °C}$	Industrial	1.8 – 5%	1.8 + 5%	V
V_{CCO}	Supply voltage relative to GND, $T_J = 0\text{ °C to }+85\text{ °C}$	Commercial	1.2	3.6	V
	Supply voltage relative to GND, $T_J = -40\text{ °C to }+100\text{ °C}$	Industrial	1.2	3.6	V
T_{IN}	Input signal transition time			250	ns

CLB Switching Characteristics

Delays originating at F/G inputs vary slightly according to the input used, see [Figure 2](#). The values listed below are worst-case. Precise values are provided by the timing analyzer.

		Speed Grade ⁽¹⁾				Units
Description	Symbol	Min	-8	-7	-6	
Combinatorial Delays						
4-input function: F/G inputs to X/Y outputs	T _{ILO}	0.19	0.40	0.42	0.47	ns, max
5-input function: F/G inputs to F5 output	T _{IF5}	0.36	0.76	0.8	0.9	ns, max
5-input function: F/G inputs to X output	T _{IF5X}	0.35	0.74	0.8	0.9	ns, max
6-input function: F/G inputs to Y output via F6 MUX	T _{IF6Y}	0.35	0.74	0.9	1.0	ns, max
6-input function: F5IN input to Y output	T _{F5INY}	0.04	0.11	0.20	0.22	ns, max
Incremental delay routing through transparent latch to XQ/YQ outputs	T _{IFNCTL}	0.27	0.63	0.7	0.8	ns, max
BY input to YB output	T _{BYYB}	0.19	0.38	0.46	0.51	ns, max
Sequential Delays						
FF Clock CLK to XQ/YQ outputs	T _{CKO}	0.34	0.78	0.9	1.0	ns, max
Latch Clock CLK to XQ/YQ outputs	T _{CKLO}	0.40	0.77	0.9	1.0	ns, max
Setup and Hold Times before/after Clock CLK						
4-input function: F/G Inputs	T _{ICK} / T _{CKI}	0.39 / 0	0.9 / 0	1.0 / 0	1.1 / 0	ns, min
5-input function: F/G inputs	T _{IF5CK} / T _{CKIF5}	0.55 / 0	1.3 / 0	1.4 / 0	1.5 / 0	ns, min
6-input function: F5IN input	T _{F5INCK} / T _{CKF5IN}	0.27 / 0	0.6 / 0	0.8 / 0	0.8 / 0	ns, min
6-input function: F/G inputs via F6 MUX	T _{IF6CK} / T _{CKIF6}	0.58 / 0	1.3 / 0	1.5 / 0	1.6 / 0	ns, min
BX/BY inputs	T _{DICK} / T _{CKDI}	0.25 / 0	0.6 / 0	0.7 / 0	0.8 / 0	ns, min
CE input	T _{CECK} / T _{CKCE}	0.28 / 0	0.55 / 0	0.7 / 0	0.7 / 0	ns, min
SR/BY inputs (synchronous)	T _{RCK} / T _{CKR}	0.24 / 0	0.46 / 0	0.52 / 0	0.6 / 0	ns, min
Clock CLK						
Minimum Pulse Width, High	T _{CH}	0.56	1.2	1.3	1.4	ns, min
Minimum Pulse Width, Low	T _{CL}	0.56	1.2	1.3	1.4	ns, min
Set/Reset						
Minimum Pulse Width, SR/BY inputs	T _{RPW}	0.94	1.9	2.1	2.4	ns, min
Delay from SR/BY inputs to XQ/YQ outputs (asynchronous)	T _{RQ}	0.39	0.8	0.9	1.0	ns, max
Toggle Frequency (MHz) (for export control)	F _{TOG}	-	416	400	357	MHz

Notes:

1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.

Table 6: PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E

Pin #	Pin Description	Bank
P173	IO_L16N_Y	2
P171	IO_VREF_L17P_Y	2
P170	IO_L17N_Y	2
P169	IO	2
P168 ¹	IO_VREF_L18P_Y	2
P167	IO_D1_L18N_Y	2
P163	IO_D2_L19P_YY	2
P162	IO_L19N_YY	2
P161	IO	2
P160	IO_L20P_Y	2
P159	IO_L20N_Y	2
P157	IO_VREF_L21P_Y	2
P156	IO_D3_L21N_Y	2
P155	IO_L22P_Y	2
P154 ³	IO_VREF_L22N_Y	2
P153	IO_L23P_YY	2
P152	IO_L23N_YY	2
P149	IO	3
P147 ³	IO_VREF	3
P145	IO_D4_L24P_Y	3
P144	IO_VREF_L24N_Y	3
P142	IO_L25P_Y	3
P141	IO_L25N_Y	3
P140	IO	3
P139	IO_L26P_YY	3
P138	IO_D5_L26N_YY	3
P134	IO_D6_L27P_Y	3
P133 ¹	IO_VREF_L27N_Y	3
P132	IO	3
P131	IO_L28P_Y	3
P130	IO_VREF_L28N_Y	3
P128	IO_L29P_Y	3
P127	IO_L29N_Y	3
P126 ²	IO_VREF_L30P_Y	3

Table 6: PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E

Pin #	Pin Description	Bank
P125	IO_L30N_Y	3
P124	IO_D7_L31P_YY	3
P123	IO_INIT_L31N_YY	3
P118	IO_L32P_YY	4
P117	IO_L32N_YY	4
P115 ²	IO_VREF	4
P114	IO_L33P_YY	4
P113	IO_L33N_YY	4
P111	IO_VREF_L34P_YY	4
P110	IO_L34N_YY	4
P109	IO	4
P108 ¹	IO_VREF_L35P_YY	4
P107	IO_L35N_YY	4
P103	IO_L36P_YY	4
P102	IO_L36N_YY	4
P101	IO	4
P100	IO_L37P_Y	4
P99	IO_L37N_Y	4
P97	IO_VREF_L38P_Y	4
P96	IO_L38N_Y	4
P95	IO_L39P_Y	4
P94 ³	IO_VREF_L39N_Y	4
P93	IO_LVDS_DLL_L40P	4
P92	GCK0	4
P89	GCK1	5
P87	IO_LVDS_DLL_L40N	5
P86 ³	IO_VREF	5
P84	IO_VREF_L41P_Y	5
P82	IO_L41N_Y	5
P81	IO	5
P80	IO	5
P79	IO_L42P_YY	5
P78	IO_L42N_YY	5

Table 6: PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E

Pin #	Pin Description	Bank
P137	VCCINT	NA
P104	VCCINT	NA
P88	VCCINT	NA
P77	VCCINT	NA
P43	VCCINT	NA
P32	VCCINT	NA
P16	VCCINT	NA
P240	VCCO	7
P232	VCCO	0
P226	VCCO	0
P212	VCCO	0
P207	VCCO	1
P197	VCCO	1
P180	VCCO	1
P176	VCCO	2
P165	VCCO	2
P150	VCCO	2
P146	VCCO	3
P136	VCCO	3
P121	VCCO	3
P116	VCCO	4
P105	VCCO	4
P90	VCCO	4
P85	VCCO	5
P76	VCCO	5
P61	VCCO	5
P55	VCCO	6
P44	VCCO	6
P30	VCCO	6
P25	VCCO	7
P15	VCCO	7
P233	GND	NA
P227	GND	NA

Table 6: PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E

Pin #	Pin Description	Bank
P219	GND	NA
P211	GND	NA
P204	GND	NA
P196	GND	NA
P190	GND	NA
P182	GND	NA
P172	GND	NA
P166	GND	NA
P158	GND	NA
P151	GND	NA
P143	GND	NA
P135	GND	NA
P129	GND	NA
P119	GND	NA
P112	GND	NA
P106	GND	NA
P98	GND	NA
P91	GND	NA
P83	GND	NA
P75	GND	NA
P69	GND	NA
P59	GND	NA
P51	GND	NA
P45	GND	NA
P37	GND	NA
P29	GND	NA
P22	GND	NA
P14	GND	NA
P8	GND	NA
P1	GND	NA

Notes:

1. V_{REF} or I/O option only in the XCV100E, 200E, 300E, 400E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV200E, 300E, 400E; otherwise, I/O option only.
3. V_{REF} or I/O option only in the XCV400E; otherwise, I/O option only.

PQ240 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A $\checkmark$ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 7: PQ240 Differential Pin Pair Summary
XCV50E, XCV100E, XCV200E, XCV300E, XCV400E

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	P92	P93	NA	IO_DLL_L40P
1	5	P89	P87	NA	IO_DLL_L40N
2	1	P210	P209	NA	IO_DLL_L6P
3	0	P213	P215	NA	IO_DLL_L6N
IO LVDS					
Total Pairs: 64, Asynchronous Outputs Pairs: 27					
0	0	P236	P237	1	VREF
1	0	P234	P235	$\checkmark$	-
2	0	P228	P229	$\checkmark$	VREF
3	0	P223	P224	$\checkmark$	-
4	0	P220	P221	3	-
5	0	P217	P218	3	VREF
6	1	P209	P215	NA	IO_LVDS_DLL
7	1	P205	P206	3	VREF
8	1	P202	P203	3	-
9	1	P199	P200	$\checkmark$	-
10	1	P194	P195	$\checkmark$	VREF
11	1	P191	P192	$\checkmark$	VREF
12	1	P188	P189	$\checkmark$	-
13	1	P186	P187	1	VREF
14	1	P184	P185	$\checkmark$	CS
15	2	P178	P177	$\checkmark$	DIN, D0

Table 7: PQ240 Differential Pin Pair Summary
XCV50E, XCV100E, XCV200E, XCV300E, XCV400E

Pair	Bank	P Pin	N Pin	AO	Other Functions
16	2	P174	P173	2	-
17	2	P171	P170	3	VREF
18	2	P168	P167	4	D1, VREF
19	2	P163	P162	$\checkmark$	D2
20	2	P160	P159	2	-
21	2	P157	P156	4	D3, VREF
22	2	P155	P154	5	VREF
23	2	P153	P152	$\checkmark$	-
24	3	P145	P144	4	D4, VREF
25	3	P142	P141	2	-
26	3	P139	P138	$\checkmark$	D5
27	3	P134	P133	4	VREF
28	3	P131	P130	3	VREF
29	3	P128	P127	2	-
30	3	P126	P125	6	VREF
31	3	P124	P123	$\checkmark$	INIT
32	4	P118	P117	$\checkmark$	-
33	4	P114	P113	$\checkmark$	-
34	4	P111	P110	$\checkmark$	VREF
35	4	P108	P107	$\checkmark$	VREF
36	4	P103	P102	$\checkmark$	-
37	4	P100	P99	3	-
38	4	P97	P96	3	VREF
39	4	P95	P94	7	VREF
40	5	P93	P87	NA	IO_LVDS_DLL
41	5	P84	P82	8	VREF
42	5	P79	P78	$\checkmark$	-
43	5	P74	P73	$\checkmark$	VREF
44	5	P71	P70	$\checkmark$	VREF
45	5	P68	P67	$\checkmark$	-
46	5	P66	P65	1	VREF
47	5	P64	P63	$\checkmark$	-

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
4	IO_L104N_YY	AJ12	
4	IO_L105P_Y	AN11	
4	IO_L105N_Y	AK12	
4	IO_L106P_YY	AL12	
4	IO_L106N_YY	AM12	
4	IO_VREF_L107P_YY	AK13	3
4	IO_L107N_YY	AL13	
4	IO_L108P_Y	AM13	
4	IO_L108N_Y	AN13	
4	IO_L109P_YY	AJ14	
4	IO_L109N_YY	AK14	
4	IO_VREF_L110P_YY	AM14	
4	IO_L110N_YY	AN15	
4	IO_L111P_Y	AJ15	
4	IO_L111N_Y	AK15	
4	IO_L112P_Y	AL15	
4	IO_L112N_Y	AM16	
4	IO_VREF_L113P_Y	AL16	
4	IO_L113N_Y	AJ16	
4	IO_L114P_Y	AK16	
4	IO_VREF_L114N_Y	AN17	2
4	IO_LVDS_DLL_L115P	AM17	
5	GCK1	AJ17	
5	IO	AL25	
5	IO	AL28	
5	IO	AL30	
5	IO	AN28	
5	IO_LVDS_DLL_L115N	AM18	
5	IO_VREF	AL18	2
5	IO_L116P_Y	AK18	
5	IO_VREF_L116N_Y	AJ18	
5	IO_L117P_Y	AN19	
5	IO_L117N_Y	AL19	
5	IO_L118P_Y	AK19	

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
5	IO_L118N_Y	AM20	
5	IO_L119P_YY	AJ19	
5	IO_VREF_L119N_YY	AL20	
5	IO_L120P_YY	AN21	
5	IO_L120N_YY	AL21	
5	IO_L121P_Y	AJ20	
5	IO_L121N_Y	AM22	
5	IO_L122P_YY	AK21	
5	IO_VREF_L122N_YY	AN23	3
5	IO_L123P_YY	AJ21	
5	IO_L123N_YY	AM23	
5	IO_L124P_Y	AK22	
5	IO_L124N_Y	AM24	
5	IO_L125P_YY	AL23	
5	IO_L125N_YY	AJ22	
5	IO_L126P_YY	AK23	
5	IO_VREF_L126N_YY	AL24	
5	IO_L127P_Y	AN26	
5	IO_L127N_Y	AJ23	
5	IO_L128P_Y	AK24	
5	IO_VREF_L128N_Y	AM26	4
5	IO_L129P_Y	AM27	
5	IO_L129N_Y	AJ24	
5	IO_L130P_Y	AL26	
5	IO_VREF_L130N_Y	AK25	1
5	IO_L131P_YY	AN29	
5	IO_VREF_L131N_YY	AJ25	
5	IO_L132P_YY	AK26	
5	IO_L132N_YY	AM29	
5	IO_L133P_Y	AM30	
5	IO_L133N_Y	AJ26	
5	IO_L134P_YY	AK27	
5	IO_VREF_L134N_YY	AL29	
5	IO_L135P_YY	AN31	
5	IO_L135N_YY	AJ27	

Table 18: FG456 — XCV200E and XCV300E

Bank	Pin Description	Pin #
7	IO	J1
7	IO	J4
7	IO	L2 ¹
7	IO_L104N_YY	L3
7	IO_L104P_YY	L4
7	IO_L105N_YY	L5
7	IO_L105P_YY	L1
7	IO_L106N_Y	L6
7	IO_L106P_Y	K2
7	IO_L107N_Y	K4
7	IO_VREF_L107P_Y	K3
7	IO_L108N_YY	K1
7	IO_L108P_YY	K5
7	IO_L109N_YY	J3
7	IO_L109P_YY	J2
7	IO_L110N_YY	J5
7	IO_L110P_YY	H1
7	IO_L111N_YY	H2
7	IO_L111P_YY	H3
7	IO_L112N_Y	G1
7	IO_VREF_L112P_Y	H4
7	IO_L113N_Y	F1
7	IO_L113P_Y	F2
7	IO_L114N_YY	H5
7	IO_L114P_YY	G3
7	IO_L115N_YY	E1
7	IO_VREF_L115P_YY	E2
7	IO_L116N_YY	F3
7	IO_L116P_YY	G5
7	IO_L117N_YY	E3
7	IO_VREF_L117P_YY	D2
7	IO_L118N_YY	F5
7	IO_L118P_YY	C1
2	CCLK	B22
3	DONE	Y19
NA	DXN	Y5

Table 18: FG456 — XCV200E and XCV300E

Bank	Pin Description	Pin #
NA	DXP	V6
NA	M0	AB2
NA	M1	U5
NA	M2	Y4
NA	PROGRAM	W20
NA	TCK	C4
NA	TDI	B20
2	TDO	A21
NA	TMS	D3
NA	NC	W19
NA	NC	W4
NA	NC	D19
NA	NC	D4
NA	VCCINT	E5
NA	VCCINT	E18
NA	VCCINT	F6
NA	VCCINT	F17
NA	VCCINT	G7
NA	VCCINT	G8
NA	VCCINT	G9
NA	VCCINT	G14
NA	VCCINT	G15
NA	VCCINT	H7
NA	VCCINT	G16
NA	VCCINT	H16
NA	VCCINT	J7
NA	VCCINT	J16
NA	VCCINT	P7
NA	VCCINT	P16
NA	VCCINT	R7
NA	VCCINT	R16
NA	VCCINT	T7
NA	VCCINT	T8
NA	VCCINT	T9
NA	VCCINT	T14

Table 22: FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
7	IO_L234N_YY	K38
7	IO_L234P_YY	L37
7	IO_L235N_YY	J39
7	IO_VREF_L235P_YY	L36
7	IO_L236N	J38
7	IO_L236P	K37
7	IO_L237N	H39
7	IO_VREF_L237P	K36 ³
7	IO_L238N_YY	H38
7	IO_L238P_YY	J37
7	IO_L239N_YY	G39
7	IO_VREF_L239P_YY	G38
7	IO_L240N_Y	J36
7	IO_L240P_Y	F39
7	IO_L241N	H37
7	IO_L241P	F38
7	IO_L242N_YY	H36
7	IO_L242P_YY	E39
7	IO_L243N_Y	G37
7	IO_VREF_L243P_Y	E38
7	IO_L244N	G36
7	IO_L244P	D39
7	IO_L245N	D38
7	IO_VREF_L245P	F36 ¹
7	IO_L246N_Y	D37
7	IO_L246P_Y	E37
2	CCLK	E4
3	DONE	AU5
NA	DXN	AV37
NA	DXP	AU35
NA	M0	AT37
NA	M1	AU38
NA	M2	AT35
NA	PROGRAM	AT5
NA	TCK	C36

Table 22: FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
NA	TDI	B3
2	TDO	C4
NA	TMS	E36
NA	VCCINT	E8
NA	VCCINT	E9
NA	VCCINT	E15
NA	VCCINT	E16
NA	VCCINT	E24
NA	VCCINT	E25
NA	VCCINT	E31
NA	VCCINT	E32
NA	VCCINT	H5
NA	VCCINT	H35
NA	VCCINT	J5
NA	VCCINT	J35
NA	VCCINT	R5
NA	VCCINT	R35
NA	VCCINT	T5
NA	VCCINT	T35
NA	VCCINT	AD5
NA	VCCINT	AD35
NA	VCCINT	AE5
NA	VCCINT	AE35
NA	VCCINT	AL5
NA	VCCINT	AL35
NA	VCCINT	AM5
NA	VCCINT	AM35
NA	VCCINT	AR8
NA	VCCINT	AR9
NA	VCCINT	AR15
NA	VCCINT	AR16
NA	VCCINT	AR24
NA	VCCINT	AR25
NA	VCCINT	AR31
NA	VCCINT	AR32

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
0	IO_L6N_Y	A5
0	IO_L6P_Y	F8
0	IO_L7N_Y	D7
0	IO_L7P_Y	N11
0	IO_L8N_YY	G9
0	IO_L8P_YY	E8
0	IO_VREF_L9N_YY	A6
0	IO_L9P_YY	J11
0	IO_L10N_Y	C7
0	IO_L10P_Y	B7
0	IO_L11N_Y	C8
0	IO_L11P_Y	H10
0	IO_L12N_YY	G10
0	IO_L12P_YY	F10
0	IO_VREF_L13N_YY	A8
0	IO_L13P_YY	H11
0	IO_L14N	D9 ⁴
0	IO_L14P	C9 ³
0	IO_L15N_YY	B9
0	IO_L15P_YY	J12
0	IO_L16N	E10 ⁴
0	IO_VREF_L16P	A9
0	IO_L17N	G11
0	IO_L17P	B10
0	IO_L18N_YY	H12 ⁴
0	IO_L18P_YY	C10 ⁴
0	IO_L19N_Y	H13
0	IO_L19P_Y	F11
0	IO_L20N_Y	E11
0	IO_L20P_Y	D11
0	IO_L21N_Y	B11 ⁴
0	IO_L21P_Y	G12 ⁴
0	IO_L22N_YY	F12
0	IO_L22P_YY	C11
0	IO_VREF_L23N_YY	A10 ¹
0	IO_L23P_YY	D12
0	IO_L24N_Y	E12

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
0	IO_L24P_Y	A11
0	IO_L25N_Y	G13
0	IO_L25P_Y	B12
0	IO_L26N_YY	A12
0	IO_L26P_YY	K13
0	IO_VREF_L27N_YY	F13
0	IO_L27P_YY	B13
0	IO_L28N_Y	G14
0	IO_L28P_Y	E13
0	IO_L29N_Y	D14
0	IO_L29P_Y	B14
0	IO_L30N_YY	A14
0	IO_L30P_YY	J14
0	IO_VREF_L31N_YY	K14
0	IO_L31P_YY	J15
0	IO_L32N	B15 ⁴
0	IO_L32P	H15 ³
0	IO_VREF_L33N_YY	F15 ^{2,3}
0	IO_L33P_YY	D15 ⁴
0	IO_LVDS_DLL_L34N	A15
1	GCK2	E15
1	IO	A25 ⁴
1	IO	B17 ⁴
1	IO	B18 ⁴
1	IO	C23 ⁴
1	IO	D16 ⁴
1	IO	D17 ⁵
1	IO	D23 ⁴
1	IO	E19 ⁴
1	IO	E24 ⁵
1	IO	F22 ⁴
1	IO	G17 ⁵
1	IO	G20 ⁴
1	IO	J16 ⁴
1	IO	J17 ⁴
1	IO	J19 ⁵

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
4	IO_L154N	AG23
4	IO_L155P_YY	AF22
4	IO_L155N_YY	AE22
4	IO_VREF_L156P_YY	AJ22
4	IO_L156N_YY	AG22
4	IO_L157P	AK24 ⁴
4	IO_L157N	AD20 ³
4	IO_L158P_YY	AA19
4	IO_L158N_YY	AF21
4	IO_L159P	AH22 ⁴
4	IO_VREF_L159N	AA18
4	IO_L160P	AG21
4	IO_L160N	AK23
4	IO_L161P_YY	AH21 ⁴
4	IO_L161N_YY	AD19 ⁴
4	IO_L162P	AE20
4	IO_L162N	AJ21
4	IO_L163P	AG20
4	IO_L163N	AF20
4	IO_L164P	AC18 ⁴
4	IO_L164N	AF19 ⁴
4	IO_L165P_YY	AJ20
4	IO_L165N_YY	AE19
4	IO_VREF_L166P_YY	AK22 ¹
4	IO_L166N_YY	AH20
4	IO_L167P	AG19
4	IO_L167N	AB17
4	IO_L168P	AJ19
4	IO_L168N	AD17
4	IO_L169P_YY	AA16
4	IO_L169N_YY	AA17
4	IO_VREF_L170P_YY	AK21
4	IO_L170N_YY	AB16
4	IO_L171P	AG18
4	IO_L171N	AK20
4	IO_L172P	AK19
4	IO_L172N	AD16

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
4	IO_L173P_YY	AE16
4	IO_L173N_YY	AE17
4	IO_VREF_L174P_YY	AG17
4	IO_L174N_YY	AJ17
4	IO_L175P	AD15 ⁴
4	IO_L175N	AH17 ³
4	IO_VREF_L176P_YY	AG16 ²
4	IO_L176N_YY	AK17
4	IO_LVDS_DLL_L177P	AF16
5	GCK1	AK16
5	IO	AA11 ⁴
5	IO	AA14 ⁴
5	IO	AD14 ⁴
5	IO	AE7 ⁵
5	IO	AE8 ⁵
5	IO	AE10 ⁴
5	IO	AF6 ⁴
5	IO	AF10 ⁴
5	IO	AG9 ⁴
5	IO	AG12 ⁴
5	IO	AG14 ⁵
5	IO	AH8 ⁴
5	IO	AK6 ⁵
5	IO	AK14 ⁵
5	IO	AJ13 ⁴
5	IO	AJ15 ⁴
5	IO_LVDS_DLL_L177N	AH16
5	IO_L178P_YY	AC15 ⁴
5	IO_VREF_L178N_YY	AG15 ^{2,3}
5	IO_L179P_YY	AB15
5	IO_L179N_YY	AF15
5	IO_L180P_YY	AA15
5	IO_VREF_L180N_YY	AF14
5	IO_L181P_YY	AH15
5	IO_L181N_YY	AK15
5	IO_L182P	AB14

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
7	IO	E3
7	IO	F1 ⁴
7	IO	G1 ⁵
7	IO	G4 ⁵
7	IO	H3 ⁵
7	IO	J1 ⁴
7	IO	J3 ⁴
7	IO	J4 ⁴
7	IO	J6 ⁴
7	IO	L10 ⁴
7	IO	N2 ⁴
7	IO	N8 ⁴
7	IO	N10 ⁴
7	IO	P3 ⁵
7	IO	P9 ⁴
7	IO	R1 ⁵
7	IO	T3 ⁴
7	IO_L247P	R10
7	IO_L248N_YY	R5 ³
7	IO_L248P_YY	R6 ⁴
7	IO_L249N_YY	R8
7	IO_VREF_L249P_YY	R4 ²
7	IO_L250N_YY	R7
7	IO_L250P_YY	R3
7	IO_L251N_YY	P10
7	IO_VREF_L251P_YY	P6
7	IO_L252N_YY	P5
7	IO_L252P_YY	P2
7	IO_L253N	P7
7	IO_L253P	P4
7	IO_L254N_YY	N4
7	IO_L254P_YY	R2
7	IO_L255N_YY	N7
7	IO_VREF_L255P_YY	P1
7	IO_L256N	M6

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
7	IO_L256P	N6
7	IO_L257N_YY	N5
7	IO_L257P_YY	N1
7	IO_L258N_YY	M4
7	IO_L258P_YY	M5
7	IO_L259N	M2
7	IO_VREF_L259P	M1 ¹
7	IO_L260N_YY	L4
7	IO_L260P_YY	L2
7	IO_L261N_Y	M7 ⁴
7	IO_L261P_Y	L5 ⁴
7	IO_L262N_YY	L1
7	IO_L262P_YY	M8
7	IO_L263N	K2
7	IO_L263P	M9
7	IO_L264N	L3 ⁴
7	IO_L264P	M10 ⁴
7	IO_L265N_YY	K5
7	IO_L265P_YY	K1
7	IO_L266N_YY	L6
7	IO_VREF_L266P_YY	K3
7	IO_L267N_YY	L7
7	IO_L267P_YY	K4
7	IO_L268N_YY	L8
7	IO_L268P_YY	J5
7	IO_L269N_YY	K6
7	IO_VREF_L269P_YY	H4
7	IO_L270N_YY	H1
7	IO_L270P_YY	K7
7	IO_L271N	J7
7	IO_L271P	J2
7	IO_L272N_YY	H5
7	IO_L272P_YY	G2
7	IO_L273N_YY	L9
7	IO_VREF_L273P_YY	G5
7	IO_L274N	F3
7	IO_L274P	K8

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
2	IO_L126N_YY	T32
2	IO_VREF_L127P_Y	U29 ¹
2	IO_L127N_Y	U33
2	IO_L128P_YY	V33
2	IO_L128N_YY	U31
3	IO	V27 ³
3	IO	V31
3	IO	V32 ³
3	IO	W33
3	IO	AB25 ³
3	IO	AB26 ³
3	IO	AB31 ³
3	IO	AC31 ³
3	IO	AF34
3	IO	AG31 ³
3	IO	AG33 ³
3	IO	AG34
3	IO	AH29 ³
3	IO	AJ30 ³
3	IO_L129P_Y	V26
3	IO_VREF_L129N_Y	V30 ¹
3	IO_L130P_YY	W34
3	IO_L130N_YY	V28
3	IO_L131P_YY	W32
3	IO_VREF_L131N_YY	W30
3	IO_L132P_Y	V29
3	IO_L132N_Y	Y34
3	IO_L133P	W29 ⁵
3	IO_L133N	Y33 ⁴
3	IO_L134P_Y	W26
3	IO_L134N_Y	W28
3	IO_L135P_YY	Y31
3	IO_L135N_YY	Y30

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
3	IO_L136P_YY	AA34 ⁵
3	IO_L136N_YY	W31 ⁴
3	IO_D4_L137P_YY	AA33
3	IO_VREF_L137N_YY	Y29
3	IO_L138P_Y	W25
3	IO_L138N_Y	AB34
3	IO_L139P_Y	Y28 ⁵
3	IO_L139N_Y	AB33 ⁴
3	IO_L140P_Y	AA30
3	IO_L140N_Y	Y26
3	IO_L141P_YY	Y27
3	IO_L141N_YY	AA31
3	IO_L142P_YY	AA27 ⁵
3	IO_L142N_YY	AA29 ⁴
3	IO_L143P_Y	AB32
3	IO_VREF_L143N_Y	AB29
3	IO_L144P_Y	AA28
3	IO_L144N_Y	AC34
3	IO_L145P	Y25
3	IO_L145N	AD34
3	IO_L146P_Y	AB30
3	IO_L146N_Y	AC33
3	IO_L147P_Y	AA26
3	IO_L147N_Y	AC32
3	IO_L148P_Y	AD33
3	IO_L148N_Y	AB28
3	IO_L149P_YY	AE34
3	IO_D5_L149N_YY	AB27
3	IO_D6_L150P_YY	AE33
3	IO_VREF_L150N_YY	AC30
3	IO_L151P_Y	AA25
3	IO_L151N_Y	AE32
3	IO_L152P_YY	AE31
3	IO_L152N_YY	AD29

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
NA	VCCINT	N22
NA	VCCINT	P13
NA	VCCINT	P22
NA	VCCINT	R13
NA	VCCINT	R22
NA	VCCINT	T13
NA	VCCINT	T22
NA	VCCINT	U10
NA	VCCINT	U25
NA	VCCINT	V10
NA	VCCINT	V25
NA	VCCINT	W13
NA	VCCINT	W22
NA	VCCINT	Y13
NA	VCCINT	Y22
NA	VCCINT	AA13
NA	VCCINT	AA22
NA	VCCINT	AB13
NA	VCCINT	AB14
NA	VCCINT	AB15
NA	VCCINT	AB16
NA	VCCINT	AB19
NA	VCCINT	AB20
NA	VCCINT	AB21
NA	VCCINT	AB22
NA	VCCINT	AC12
NA	VCCINT	AC23
NA	VCCINT	AD24
NA	VCCINT	AD11
NA	VCCINT	AE10
NA	VCCINT	AE17
NA	VCCINT	AE18
NA	VCCINT	AE25

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
NA	VCCO_0	M17
NA	VCCO_0	L17
NA	VCCO_0	L16
NA	VCCO_0	E10
NA	VCCO_0	C14
NA	VCCO_0	A6
NA	VCCO_0	M13
NA	VCCO_0	M14
NA	VCCO_0	M15
NA	VCCO_0	M16
NA	VCCO_0	L12
NA	VCCO_0	L13
NA	VCCO_0	L14
NA	VCCO_0	L15
NA	VCCO_1	M18
NA	VCCO_1	L18
NA	VCCO_1	L23
NA	VCCO_1	E25
NA	VCCO_1	C21
NA	VCCO_1	A29
NA	VCCO_1	M19
NA	VCCO_1	M20
NA	VCCO_1	M21
NA	VCCO_1	M22
NA	VCCO_1	L19
NA	VCCO_1	L20
NA	VCCO_1	L21
NA	VCCO_1	L22
NA	VCCO_2	U24
NA	VCCO_2	U23
NA	VCCO_2	N24
NA	VCCO_2	M24
NA	VCCO_2	K30
NA	VCCO_2	F34

Table 29: FG1156 Differential Pin Pair Summary:
XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Pair	Bank	P Pin	N Pin	AO	Other Functions
311	7	P2	R8	2600 2000 1000	-
312	7	N1	R9	3200 2600 2000	-
313	7	R10	P4	3200 2600 1600 1000	-
314	7	N2	P8	3200 2600 2000 1600 1000	-
315	7	P7	P6	3200 2600 2000 1600	-
316	7	N4	M1	2600 2000 1000	VREF
317	7	N3	N6	3200 1600 1000	-
318	7	M2	P9	2600 1600	-
319	7	M3	N7	3200 2600 1600 1000	-
320	7	M4	P10	2000 1000	-
321	7	N8	L1	3200 2600 2000	-
322	7	N9	L2	3200 2600 2000 1600 1000	-
323	7	K1	M7	2000 1600 1000	VREF
324	7	L4	M8	3200 1600 1000	-
325	7	L5	J1	3200 2600 2000 1600 1000	-
326	7	K3	J2	3200 2600 2000 1600 1000	VREF
327	7	J3	L7	3200 2600 1600 1000	-
328	7	H2	M9	3200 2600 1600	-
329	7	K6	J4	2600 1000	VREF
330	7	G2	L8	3200 2600 2000 1600 1000	-

Table 29: FG1156 Differential Pin Pair Summary:
XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Pair	Bank	P Pin	N Pin	AO	Other Functions
331	7	K7	H3	2000 1600	-
332	7	J5	G3	3200 2600 2000 1600 1000	VREF
333	7	H5	L9	2600 2000 1000	-
334	7	H4	J6	3200 2600 2000	-
335	7	K8	G4	3200 2600 1600 1000	-
336	7	F2	J7	3200 2600 2000 1600 1000	-
337	7	L10	F3	3200 2600 2000 1600	-
338	7	H6	E1	2600 2000 1000	VREF
339	7	E2	G5	3200 2600 1600 1000	-
340	7	D1	K9	2600 1600	-
341	7	J8	E3	3200 2600 1600 1000	VREF
342	7	D2	E4	2600 2000 1000	-
343	7	D3	F4	3200 2600 2000	-